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			2 3 4 5 6 7 8    6 7 8 9 : ; < = >    ? @ <	A B C	D E F
			改为                    最大值 流焊                    波峰焊改为回	- .	A B C
			G H I	- .	A B C
			J K L                    M N 2 O I		

/ Descriptions

P M M N Q R S T U V W

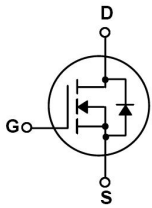
/ Features

X Y Z [ X \ ] Z Ž ^ ? \_ ` a b ) \* c d W

/ Applications

e f g h i j k l h i ^ ? W

/ Equivalent Circuit



/ Pinning



m m m m

/ Marking

n o p q r W

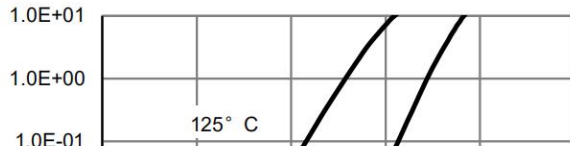
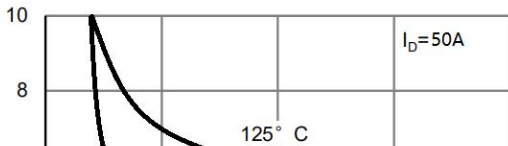
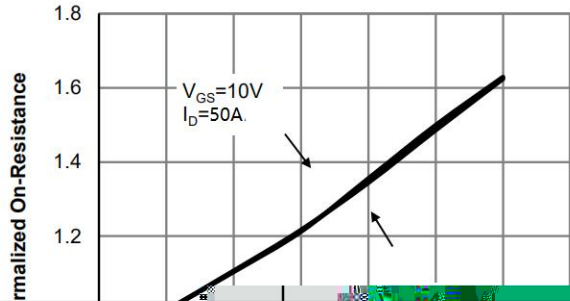
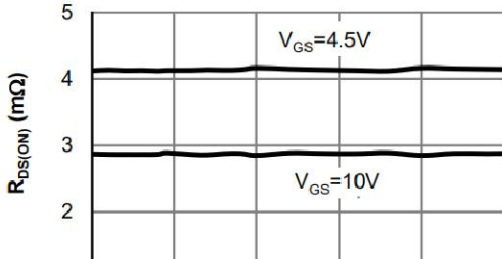
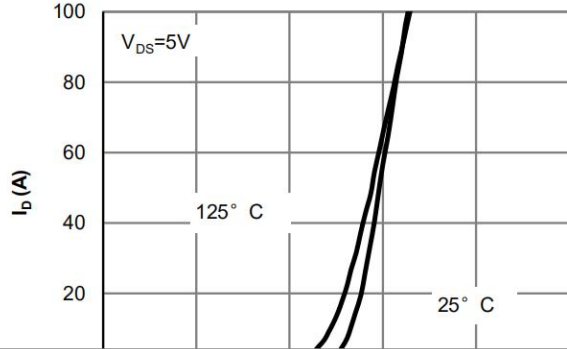
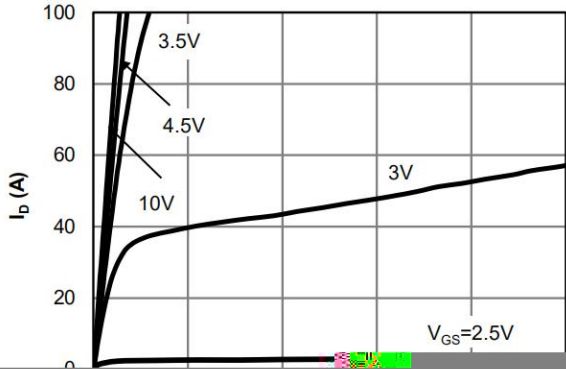
参数	符号	数值	单位
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**/ Electrical Characteristics(Ta=25 )**

参数	符号	测试条件	最小值	典型值	最大值	单位

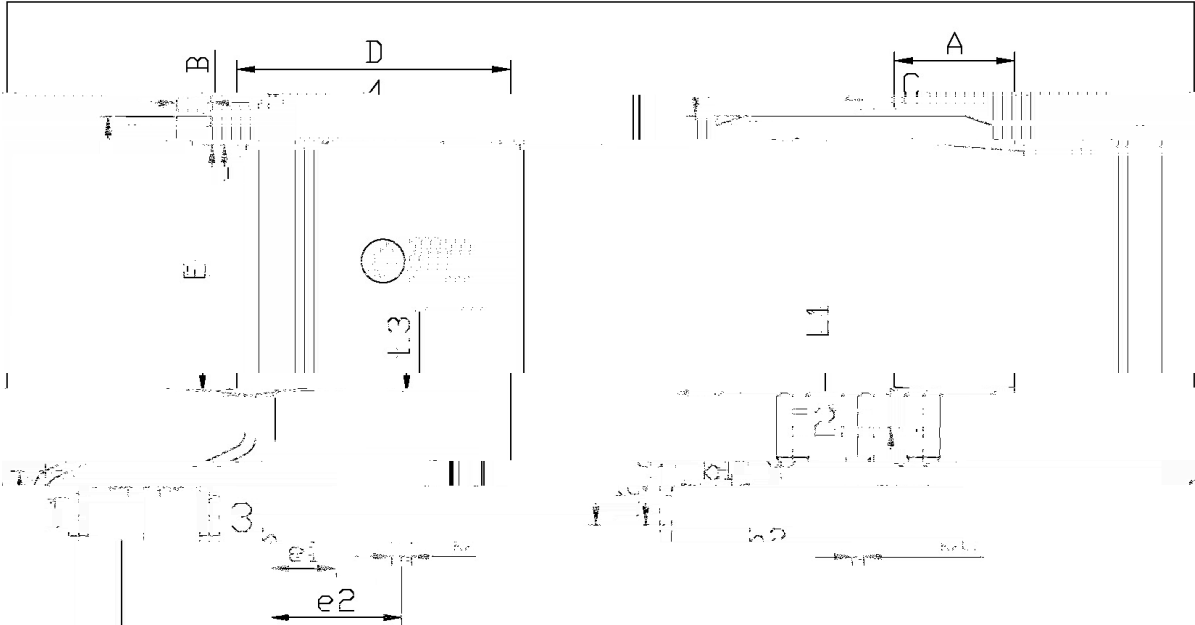


/ Electrical Characteristic Curve





/ Package Dimensions

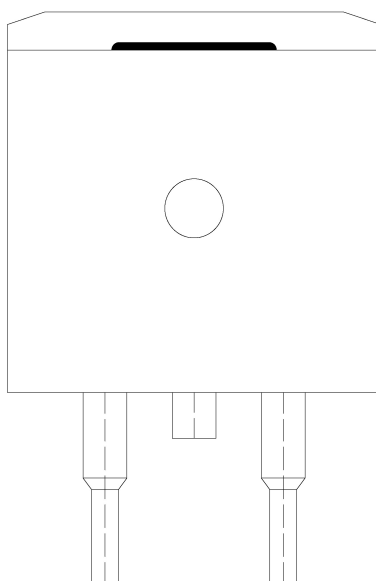


单位: mm

Dimensions	Max	Min	Max	Min
A	9.40	4.30	6.70	9.00
B	2.74	1.00	1.40	2.28
D	6.90	1.35	6.70	6.00
E	2.84	0.40	1.20	2.24
L1	1.60	1.20	1.40	1.20
L2				
L3				
e1				
e2				

TD-263

/ Marking Instructions



100N03

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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)


± °C                      ± °C                      °C  
± °C                      ± °C                      °C

/ Resistance to Soldering Heat Test Conditions

± °C                      ± °C                      °C

/ Packaging SPEC.